

描述 / Descriptions

SOT-23 塑封封装 PNP 半导体三极管。Silicon PNP transistor in a SOT-23 Plastic Package.

特征 / Features

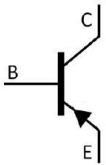
击穿电压高, 饱和压降低, 与 2SD1782K 互补。

High breakdown, low $V_{CE(sat)}$, complements the 2SD1782K.

用途 / Applications

用于一般中功率放大。

Medium power amplifier applications.

内部等效电路 / Equivalent Circuit**引脚排列 / Pinning**

PIN1 : Base

PIN 2 : Emitter

PIN 3 : Collector

放大及印章代码 / h_{FE} Classifications & Marking

h_{FE} Classifications Symbol	Q	R
h_{FE} Range	120~270	180~390
Marking	HAKQ	HAKR

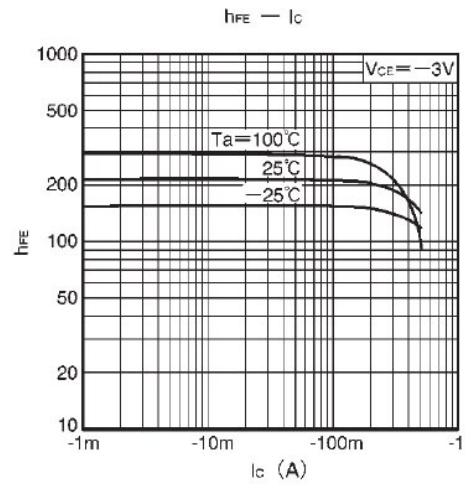
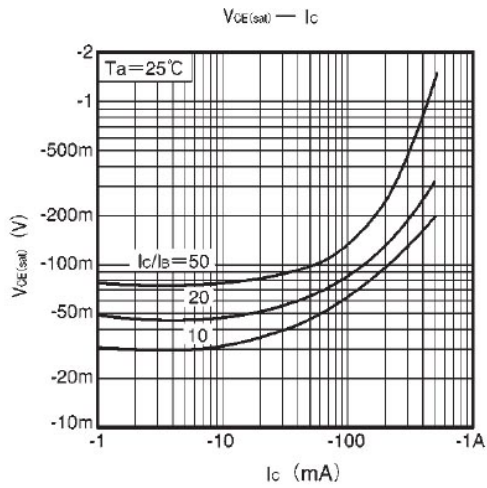
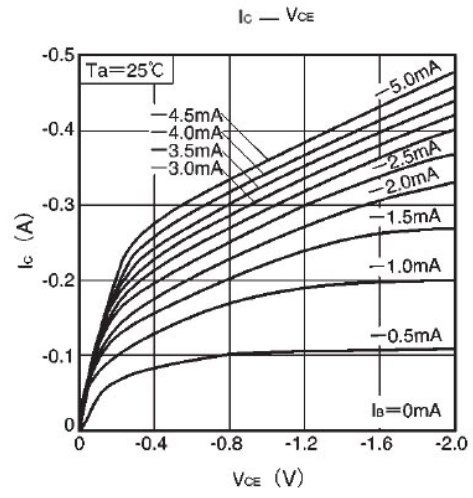
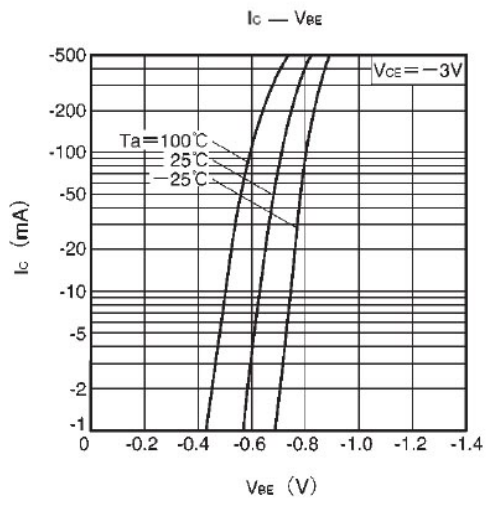
极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Collector to Base Voltage	V_{CBO}	-80	V
Collector to Emitter Voltage	V_{CEO}	-80	V
Emitter to Base Voltage	V_{EBO}	-5	V
Collector Current - Continuous	I_C	-500	mA
Collector Power Dissipation	P_C	200	mW
Junction Temperature	T_j	150	°C
Storage Temperature Range	T_{stg}	-55 ~ 150	°C

电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Collector to Base Breakdown Voltage	V_{CBO}	$I_C = -50\mu A$	-80			V
Collector to Emitter Breakdown Voltage	V_{CEO}	$I_C = -2mA$	-80			V
Emitter to Base Breakdown Voltage	V_{EBO}	$I_E = -50\mu A$	-5			V
Collector Cut-Off Current	I_{CBO}	$V_{CB} = -50V$ $I_E = 0$			-0.5	μA
Emitter Base Cut-Off Current	I_{EBO}	$V_{EB} = -4.0V$ $I_C = 0$			-0.5	μA
DC Current Gain	h_{FE}	$V_{CE} = -3.0V$ $I_C = -100mA$	120		390	
Collector to Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C = -500mA$ $I_B = -50mA$		-0.2	-0.5	V
Transition Frequency	f_T	$I_C = -50mA$ $f = 100MHz$ $V_{CE} = -10V$		180		MHz
Collector output capacitance	C_{ob}	$V_{CB} = -10V$ $I_E = 0$ $f = 1.0MHz$		11		pF

电参数曲线图 / Electrical Characteristic Curve



外形尺寸图 / Package Dimensions

SOT-23

单位: mm



印章说明 / Marking Instructions



说明：

H： 为公司代码

AK： 为型号代码

R： 为 h_{FE} 分档代码

Note:

H: Company Code

AK: Product Type Code

R: h_{FE} Classifications Symbol Code

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 25~150°C，时间 60~90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2~10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOT-23	3,000	10	30,000	6	180,000	7" x8	180×120×180	390×385×205

使用说明 / Notices